



Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at
www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.



μSerDes™ FIN212AC

12-Bit Serializer / Deserializer Supporting Cameras and Small Displays

Features

Data & Control Bits	12-Bit
Frequency	40MHz
Capability	Camera or LCD
Interface	Microcontroller, RGB, YUV
μController Usage	m68 & i86
Selectable Edge Rates	Yes
Standby Current	<10 μA
Core Voltage (V _{DDA/S})	2.5 to 3.6V
I/O Voltage (V _{DDP})	1.65 to 3.6V
ESD (I/O to GND)	14kV
Package	32-Terminal MLP 42-Ball USS-BGA
Ordering Information	FIN212ACMLX FIN212ACGFX

Description

The FIN212AC μSerDes™ is a low-power serializer / deserializer optimized for use in cell phone displays and camera paths. The device reduces a 12-bit data path to four wires. For camera applications, an additional master clock can be passed in the opposite direction of data flow. The device utilizes Fairchild's proprietary ultra-low power, low-EMI technology.

Applications

- Slider, Folder, & Clamshell Mobile Handsets
- Printers
- Security Cameras

Related Resources

- For samples and questions, please contact:
Interface@fairchildsemi.com.

Typical Application

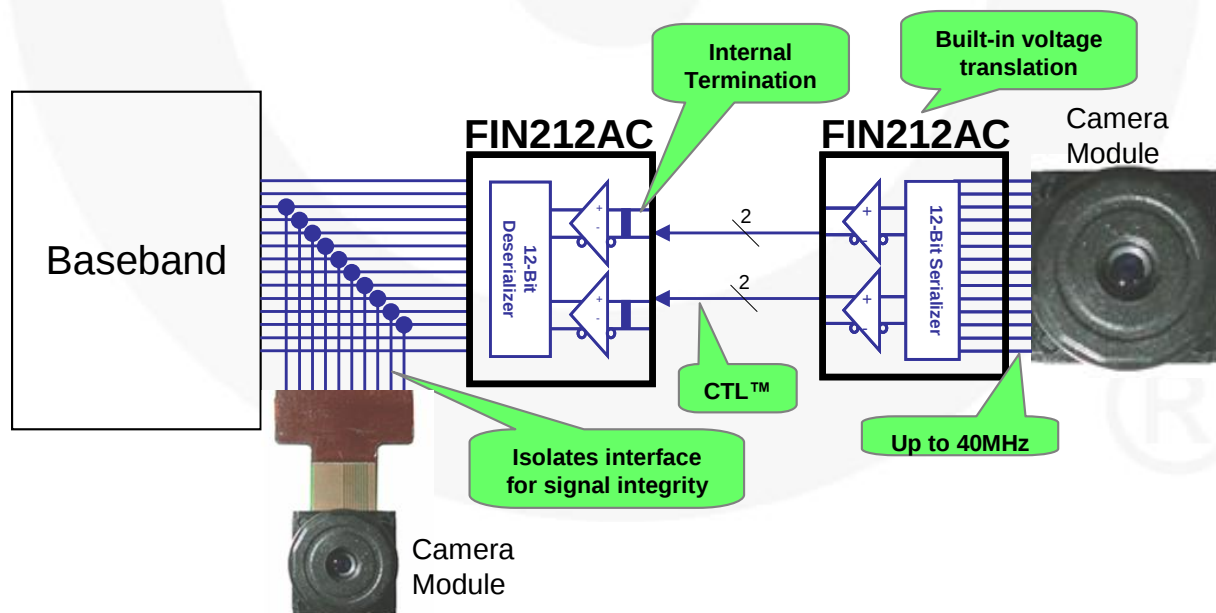


Figure 1. Mobile Phone Example

FIN212AC (Serializer DIRI=1) Pin Descriptions

Pin Name	Description	
DIRI	Control to determine serializer or deserializer configuration.	0 Deserializer 1 Serializer
CTL_ADJ	Adjusts CTL drive to compensate for environmental conditions and length.	0 Low drive (low power) 1 High drive (high power)
S0	Configure frequency range for the PLL.	See Table 1 Serializer (DIRI=1) Control Pin.
S1	Configure frequency range for the PLL.	See Table 1 Serializer (DIRI=1) Control Pin.
PLL0	Divide or adjust the serial frequency.	See Table 1 Serializer (DIRI=1) Control Pin.
PLL1	Divide or adjust the serial frequency.	See Table 1 Serializer (DIRI=1) Control Pin.
CKREF	LV-CMOS clock input and PLL reference.	
STROBE	LV-CMOS strobe input for latching data (DP [1:12]) into the serializer on the rising edge.	
DP[1:12]	LV-CMOS parallel data input. (GND input if not used)	
CKSO+	CTL Differential serializer output bit clock.	
CKSO-	CKSO+: Positive signal; CKSO-: Negative signal.	
DSO+	CTL Differential serial output data signals.	
DSO-	DSO+: Positive signal; DSO-: Negative signal.	
CKSI+	CTL Differential deserializer input bit clock.	No connect unless in "clock pass-through" mode.
CKSI-	CKSI+: Positive signal; CKSI-: Negative signal.	
CKP	LV-CMOS word clock output or Pixel clock output.	No connect unless in "clock pass-through" mode.
/DIRO	LV-CMOS output, Inversion of DIRI in normal operation. Can be used to drive the DIRI signal of the deserializer where the interface needs to be turned around.	No connect if not used.
VDDP	Power supply for parallel I/O. (All VDDP pins must be connected to VDDP)	
VDDS	Power supply for serial I/O.	
VDDA	Power supply for core.	
GND	All GND pins must be connected to ground. BGA: all GND pads. MLP: Pin 29 & GND PAD must be grounded.	
N/C	No connect. (Do not connect to GND or VDD)	

Note:

- 0=GND; 1=VDDP

FIN212AC (Serializer DIRI=1) Pin Configurations

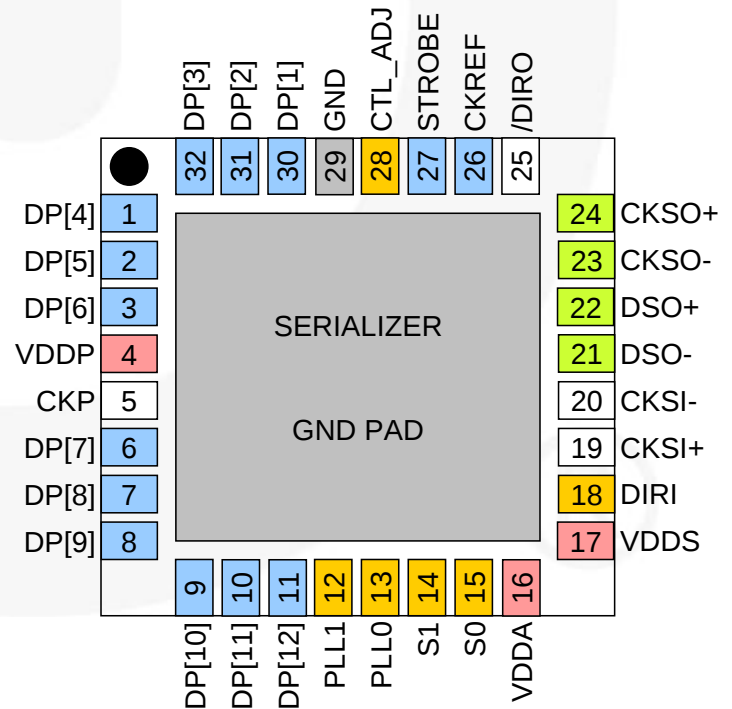
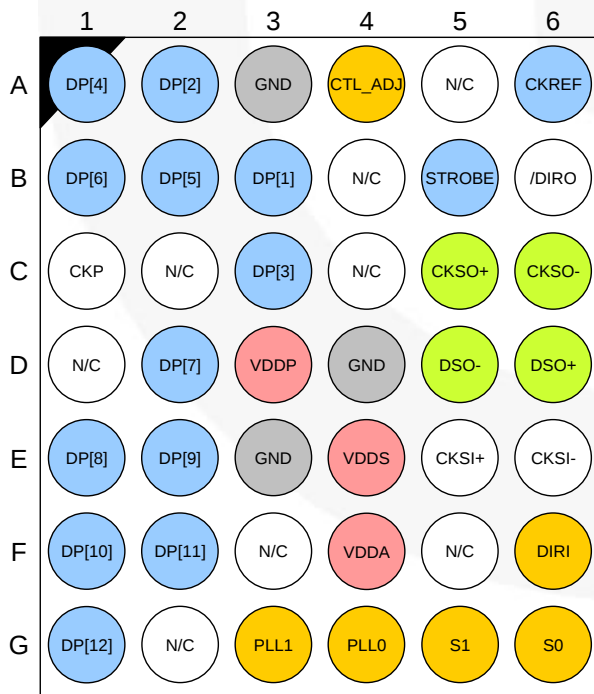


Figure 2. FIN212AC (Serializer DIRI=1) Pin Assignments (Top View)

FIN212AC (Deserializer DIRI=0) Pin Descriptions

Pin Name	Description	
DIRI	Control to determine serializer or deserializer configuration.	0 Deserializer 1 Serializer
XTERM	Control to determine if using internal or external termination	0 Internal termination used 1 External termination required on CKSI & DSI
S0	Signals used to define the edge rate of parallel I/O.	See Table 2 Deserializer (DIRI=0) Control Pin.
S1	Signals used to define the edge rate of parallel I/O.	See Table 2 Deserializer (DIRI=0) Control Pin.
PWS0	Configure CKP pulse width.	See Table 2 Deserializer (DIRI=0) Control Pin.
PWS1	Configure CKP pulse width.	See Table 2 Deserializer (DIRI=0) Control Pin.
DP[1:12]	LV-CMOS parallel data output. (N/C if not used)	
CKP	LV-CMOS word clock output or Pixel clock output.	
DSI+	CTL Differential serial input data signals.	
DSI-	DSI+: Positive signal; DSI-: Negative signal.	
CKSI+	CTL Differential deserializer input bit clock.	
CKSI-	CKSI+: Positive signal; CKSI-: Negative signal.	
CKSO+	CTL Differential serializer output bit clock.	No connect unless in "clock pass-through" mode.
CKSO-	CKSO+: Positive signal; CKSO-: Negative signal.	
CKREF	LV-CMOS clock input and PLL reference.	No connect unless in "clock pass-through" mode.
STROBE	LV-CMOS strobe input for latching data into the serializer.	No connect unless in "clock pass-through" mode.
/DIRO	LV-CMOS Output. Inversion of DIRI in normal operation.	No connect if not used.
VDDP	Power supply for parallel I/O. (All VDDP pins must be connected to VDDP)	
VDDS	Power supply for serial I/O.	
VDDA	Power supply for core.	
GND	All GND pins must be connected to ground. BGA: all GND pads. MLP: Pin 28, 29, GND PAD must be grounded.	
N/C	No connect. BGA: G1, F2; MLP: 10, 11; (Do not connect to GND or VDD)	

Note:

2. 0=GND; 1=VDDP

FIN212AC (Deserializer DIRI=0) Pin Configurations

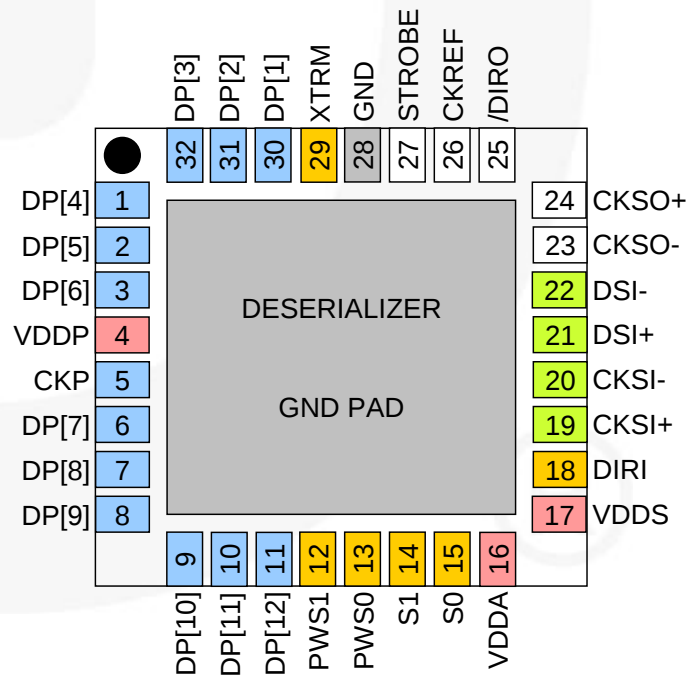
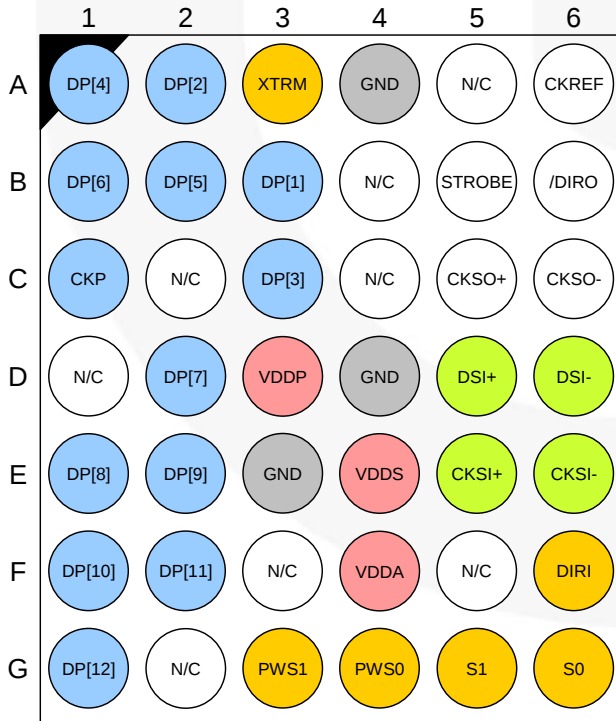


Figure 3. FIN212AC (Deserializer DIRI=0) Pin Assignments (Top View)

System Control Pin

Conditions	Function			Control Pin			
	CKREF	STROBE	PLL Multiplier	PLL0	PLL1	S0	S1
Slow Frequencies							
Normal operation	5MHz to 14MHz	≤ CKREF (Up to 14MHz)	1	1	0	0	1
Supports spread spectrum on CKREF	4.7MHz to 13.3MHz	≤ CKREF (Up to 13.3MHz)	0.954	0	0	0	1
With a fixed CKREF input; STROBE can be 1/2 the speed	5MHz to 14MHz	≤ CKREF / 2 (Up to 7MHz)	2	0	1	0	1
With a fixed CKREF input; STROBE can be 1/3 the speed	5MHz to 14MHz	≤ CKREF / 3 (Up to 4.67MHz)	3	1	1	0	1
Medium Frequencies							
Normal operation	8MHz to 28MHz	≤ CKREF (Up to 28MHz)	1	1	0	1	1
Supports spread spectrum on CKREF	9.5MHz to 26.7MHz	≤ CKREF (Up to 26.7MHz)	0.954	0	0	1	1
With a fixed CKREF input; STROBE can be 1/2 the speed	8MHz to 28MHz	≤ CKREF / 2 (Up to 14MHz)	2	0	1	1	1
With a fixed CKREF input; STROBE can be 1/3 the speed	8MHz to 28MHz	≤ CKREF / 3 (Up to 9.3MHz)	3	1	1	1	1
Fast Frequencies							
Normal operation	20MHz to 40MHz	≤ CKREF (Up to 40MHz)	1	1	0	1	0
Supports spread spectrum on CKREF	19MHz to 38.2MHz	≤ CKREF (Up to 38.2MHz)	0.954	0	0	1	0
With a fixed CKREF input; STROBE can be 1/2 the speed	20MHz to 40MHz	≤ CKREF / 2 (Up to 20MHz)	2	0	1	1	0
With a fixed CKREF input; STROBE can be 1/3 the speed	20MHz to 40MHz	≤ CKREF / 3 (Up to 13.3MHz)	3	1	1	1	0
Power-Down				X	X	0	0

Table 1: Serializer (DIRI=1) Control Pin

LVCMOS Output Edge Rates	CKP to STROBE	CKP Pulse Width Low Time		Reference		Control Pin			
		CKREF=19.2 MHz	CKREF=26 MHz	PLL Multiplier (Serializer)	Pwidth Multiplier	PWS0	PWS1	S0	S1
Slow Frequencies									
~7 – 8ns (C _L =8pF) [Typically for 5MHz to 14MHz signals]	Non-Inverted	52.1ns	38.5ns	2	7	0	0	0	1
	Inverted	52.1ns	38.5ns	2	7	1	0	0	1
	Non-Inverted	96.7ns	71.4ns	2	13	0	1	0	1
	Non-Inverted	126.5ns	93.4ns	2	17	1	1	0	1
Medium Frequencies									
~4 – 5ns (C _L =8pF) [Typically for 8MHz to 28MHz signals]	Non-Inverted	78.1ns	57.7ns	3	7	0	0	1	1
	Inverted	78.1ns	57.7ns	3	7	1	0	1	1
	Non-Inverted	145.1ns	107.1ns	3	13	0	1	1	1
	Non-Inverted	189.7ns	140.1ns	3	17	1	1	1	1
Fast Frequencies									
~2 – 3ns (C _L =8pF) [Typically for 20MHz to 40MHz signals]	Non-Inverted	26ns	19.2ns	1	7	0	0	1	0
	Inverted	26ns	19.2ns	1	7	1	0	1	0
	Non-Inverted	48.4ns	35.7ns	1	13	0	1	1	0
	Non-Inverted	63.2ns	46.7ns	1	17	1	1	1	0
Power-Down						X	X	0	0

Table 2: Deserializer (DIRI=0) Control Pin

Pulse Width Calculations

$$\text{CKP Pulse Width Low Time} = (\text{PLL Multiplier} * \text{Pwidth Multiplier}) / (\text{CKREF} * 14) \quad (1)$$

Example: CKREF=26MHz; PLL Multiplier=2; Pwidth Multiplier=13

$$\text{CKP Pulse width} = (2 * 13) / (26\text{MHz} * 14) = 71.4\text{ns} \quad (2)$$

Power-Down States

When both S1 and S0 signals are 0, regardless of the state of the DIRI signal, the FIN212AC resets and powers down. The power-down mode shuts down all internal analog circuitry, disables the serial input and output of the device, and resets all internal digital logic. Table 3: Power-Down indicates the state of the input states and output buffers in Power-Down mode.

Signal Pins	DIRI=1 (Serializer)	DIRI=0 (Deserializer)
DP[12:1]	Inputs Disabled	High-Z
CKP	HIGH	High-Z
STROBE	Input Disabled	Input Disabled
CKREF	Input Disabled	Input Disabled
/DIRO	0	1

Table 3: Power-Down

Clock Pass-Through Mode

Clock pass-through mode allows a harmonic rich clock source to be sent to the serializer in a CTL format to reduce the overall harmonic content of the phone, and can reduce the need for EMI filters. The Master Clock Pass through mode performs a translation to the clock in the CTL link, and does not serialize this signal. The following describes how to enable this functionality for an image sensor (See Figure 6).

Deserializer Configuration (DIRI=0)

1. Connect CKREF(BGA pin A6) to GROUND
2. Connect master clock to STROBE (BGA pin B5)

Serializer Configuration (DIRI=1)

1. CKSI passes master clock to CKP output (BGA pin C1)

CKREF and STROBE Signals

Please note that there is a setup and hold time between STROBE and data that must be met as seen on the electrical characteristics section. The relationship between CKREF and STROBE can be synchronous or asynchronous depending on what is available in the system. It is suggested that if the signals are synchronous and in normal operation that CKREF is tied to STROBE as close to the chip as possible. If you are running an asynchronous or spread spectrum setup, please be aware this may result on cycle jitter on the CKP signal. They cycle jitter does not effect the output data and clock relationship, the display or end application should continue to work as normal.

PLL Note

Please note that the PLL ranges can overlap, power consumption can be reduced by selecting the operation in the lower end of the higher speed PLL range.

Application Diagrams

The following application diagrams illustrate the most typical applications for the FIN212 device. Specific configurations of the control pins may vary based on the needs of a given system. The following recommendations are valid for all of the applications shown.

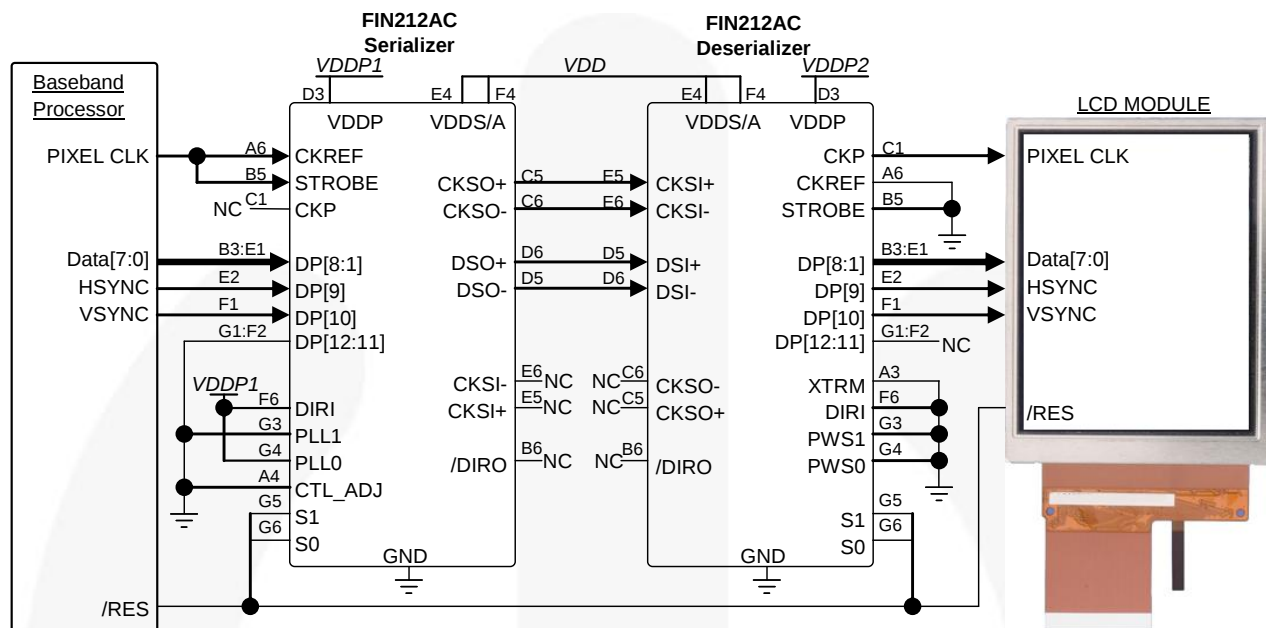


Figure 4. 8-Bit RGB Application (Example Shows BGA 42-Pin Package)

Serializer Configuration:

8MHz to 28MHz Frequency Range (S1=S0=1)
Normal Mode (PLL1=0; PLL0=1)

Deserializer Configuration:

~4 – 5ns output edge rates ($S1=S0=1$)
~50% CKP PW, ($PWS1=PWS0=0$)

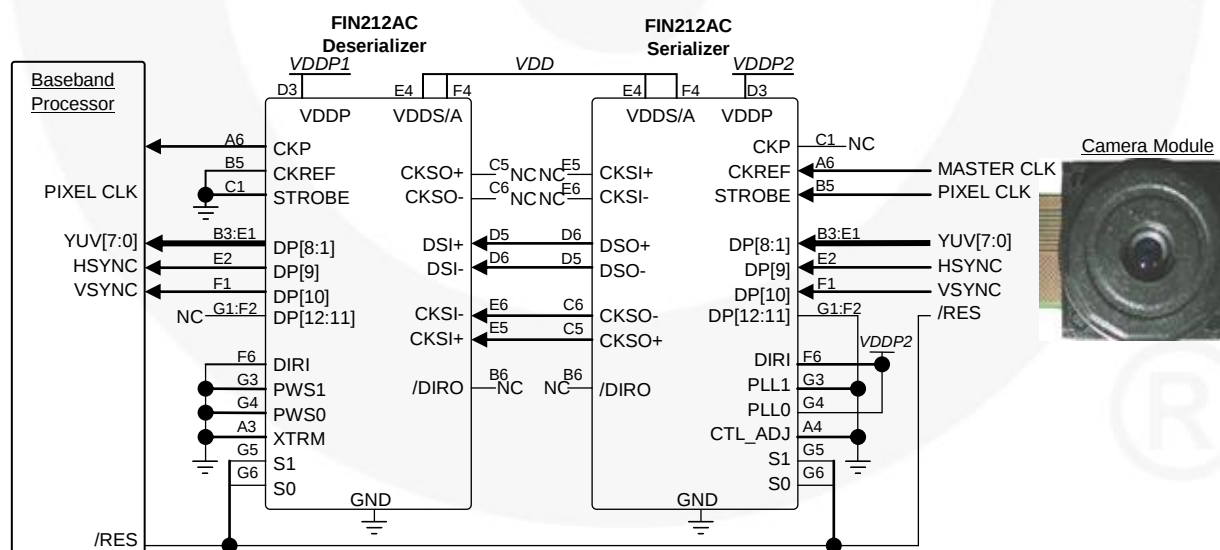


Figure 5. 8-Bit YUV 1.3MPixel CMOS Imager (Example Shows BGA 42-Pin Package)

Deserializer Configuration:

~2 – 3ns output edge rates (S1=0, S0=1)
~50% CKP PW, (PWS1=PWS0=0)

Serializer Configuration:

20MHz to 40MHz Frequency Range (S1=0, S0=1)
Normal Mode (PLL1=0, PLL0=1)

Application Diagrams (Continued)

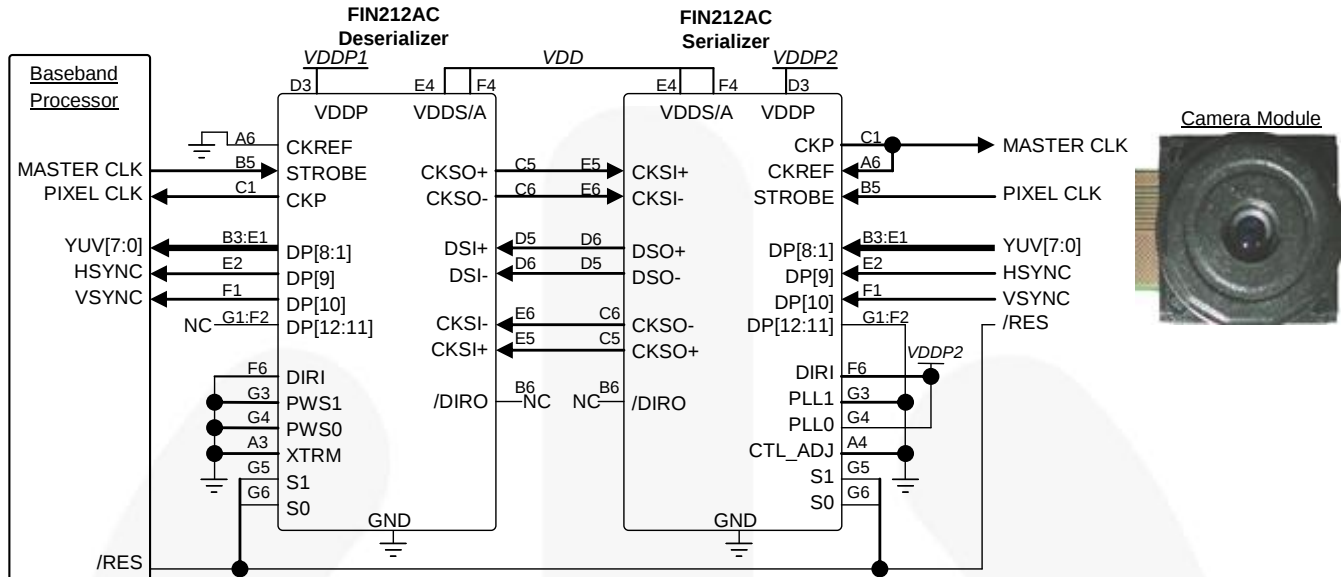


Figure 6. 8-Bit YUV 1.3MPixel CMOS Imager In Clock Pass-Through Mode

Serializer Configuration:

20MHz to 40MHz Frequency Range (S1=0, S0=1)
Normal Mode (PLL1=0; PLL0=1)
Master clock bypass mode.

Deserializer Configuration:

~2 – 3ns output edge rates (S1=0, S0=1)
~50% CKP PW,(PWS1=PWS0=0)

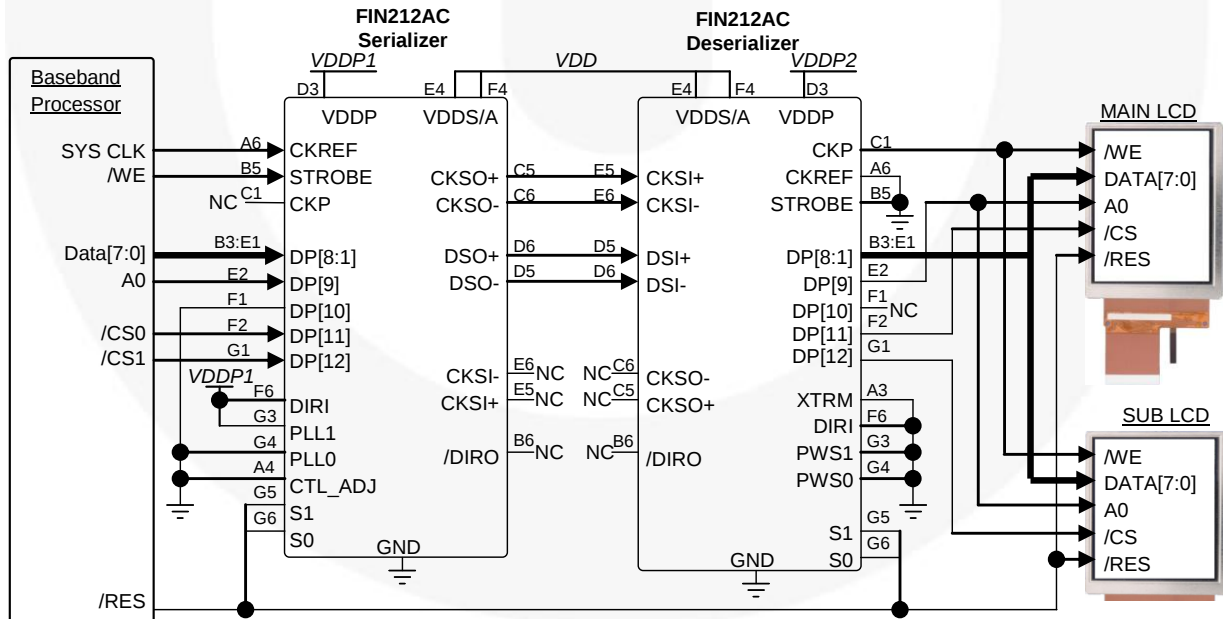


Figure 7. 8-Bit WRITE-Only Microcontroller Interface (Example Shows BGA 42-Pin Package)

Serializer Configuration:

20MHz to 40MHz Frequency Range (S1=0, S0=1)
CKREF is twice as fast STROBE (PLL1=1; PLL0=0)
CKREF=26MHz & STROBE Frequency=10 MHz

Deserializer Configuration:

~7 – 8ns output edge rates (S1=1, S0=0)
~50% CKP PW,(PWS1=PWS0=0)

Additional Application Information

Flex Cabling: The serial I/O information is transmitted at a high serial rate. Care must be taken implementing this serial I/O flex cable. The following best practices should be used when developing the flex cabling or Flex PCB.

- Keep all four differential Serial Wires the same length.
- Do not allow noisy signals over or near differential serial wires.
Example: No LVCMOS traces over differential serial wires.
- Use only one ground plane or wire over the differential serial wires. Do not run ground over top and bottom.
- Design goal of 100Ω differential characteristic impedance.
- Do not place test points on differential serial wires.
- Use differential serial wires a minimum of 2cm away from the antenna.
- For additional applications notes or flex guidelines see your sales representative or contact Fairchild directly.
- For samples and questions, please contact: Interface@fairchildsemi.com.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V _{DD}	Supply Voltage	-0.5V	+4.6	V
	All Input/Output Voltage	-0.5	V _{DD} +0.5	V
	CTL Output Short-Circuit Duration	Continuous		
T _{STG}	Storage Temperature Range	-65	+150	°C
T _J	Maximum Junction Temperature	+150		°C
T _L	Lead Temperature (Soldering, four seconds)	+260		°C
ESD	Human Body Model JESD22-A114	Serial I/O Pins to GND	14	kV
		All Pins	8	kV
	Charged Device Model, JESD22-C101		2	kV

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V _{DDA} , V _{DDS}	Supply Voltage	2.5	3.6	V
V _{DDP}	Supply Voltage	1.65	3.60	V
T _A	Operating Temperature	-30	+70	°C
V _{DDA-PP}	Supply Noise Voltage	100		mV _{PP}

DC Electrical Characteristics

Values are provided for over-supply voltage and operating temperature ranges, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min.	Typ. ⁽³⁾	Max.	Unit
LVCMOS I/O						
V _{IH}	Input High Voltage		0.65xV _{DDP}		V _{DDP}	
V _{IL}	Input Low Voltage		GND		0.35xV _{DDP}	V

DC Electrical Characteristics (Continued)

V _{OH}	Output High Voltage	I _{OH} =-2.0mA, S1=0,S0=1		0.75xV _{DDP}		V _{DDP}	V
		I _{OH} =-0.4mA, S1=1,S0=0					
		I _{OH} =-1.0mA, S1=1,S0=1					
V _{OL}	Output Low Voltage	I _{OL} =2.0mA, S1=0,S0=1		0		0.25xV _{DDP}	V
		I _{OL} =0.4mA, S1=1,S0=0					
		I _{OL} =1.0mA, S1=1,S0=1					
I _{IN}	Input Current	V _{IN} = 0V to 3.6V		-5.0		5.0	μA
DIFFERENTIAL I/O							
I _{ODH}	Output HIGH Source Current	V _{OS} =1.0V	CTL_ADJ=0		-2		mA
			CTL_ADJ=1		-3.4		
I _{ODL}	Output LOW Sink Current	V _{OS} =1.0V	CTL_ADJ=0		1.2		mA
			CTL_ADJ=1		2		
V _{GO}	Input Voltage Ground Offset ⁽⁴⁾				0		V
R _{TRM}	CKS Internal Receiver Termination Resistor	V _{ID} =50mV, V _{IC} =925mV,		80	100	120	Ω
		DIRI=0					
	DS Internal Receiver Termination Resistor	V _{ID} =50mV, V _{IC} =925mV,		80	100	120	Ω
		DIRI=0					

Notes:

- Typical values are given for $V_{DD}=2.775\text{V}$ and $T_A=25^\circ\text{C}$. Positive current values refer to the current flowing into the device and negative values refer to the current flowing out of pins. Voltages are referenced to GROUND unless otherwise specified (except ΔV_{OD} and V_{OD}).
- V_{GO} is the difference in device ground levels between the CTL driver and the CTL receiver.

Power Supply Currents

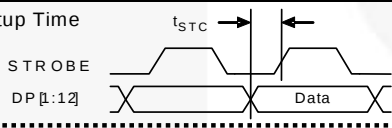
Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
I_{DD_PD}	V_{DD} Power-Down Supply Current	$S1=S0=0$, All Inputs at GND or VDD			0.1		µA
I_{DD_SER1}	Dynamic Serializer Power Supply Current	$f_{CKREF}=f_{STRB}$, $PLL1=0, PLL0=1$; $CTL_ADJ=0$; $C_L=0\text{pF}$	$S1=L$ $S0=H$	20MHz		13	mA
				40MHz		19	mA
			$S1=H$ $S0=L$	5MHz		9.5	mA
				14MHz		17	mA
			$S1=H$ $S0=H$	8MHz		11	mA
				28MHz		20	mA
I_{DD_DES1}	Dynamic Deserializer Power Supply Current	$f_{CKREF}=f_{STRB}$, $PLL1=0, PLL0=1$; $CTL_ADJ=0$; $C_L=0\text{pF}$	$S1=L$ $S0=H$	20MHz		10	mA
				40MHz		14	mA
			$S1=H$ $S0=L$	5MHz		8	mA
				14MHz		9	mA
			$S1=H$ $S0=H$	8MHz		9	mA
				28MHz		12	mA

Pin Capacitance Tables

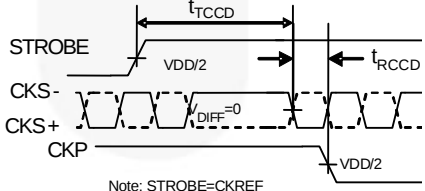
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
C_{IN} , C_{IO} , $C_{IO-DIFF}$	Capacitance of Input Only Signals; Parallel Port Pins DP[1:10]; Differential I/O	$DIRI=1$, $S1=0$, $S0=0$, $V_{DD}=2.5\text{V}$		2		pF

AC Electrical Characteristics

Values are provided for over-supply voltage and operating temperature ranges, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Serializer Input Operating Conditions						
f_{CKREF}	CKREF Clock Frequency (5MHz - >40MHz);	$f_{CKREF}=f_{STRB}$	S1=0, S0=1	18	40	MHz
			S1=1, S0=0	5	14	
			S1=1, S0=1	10	28	
f_{STRB}	Strobe Frequency Relative to CKREF Frequency	$f_{CKREF} \neq f_{STRB}$	PLL1=0, PLL0=0		100	% of f_{CKREF}
			PLL1=0, PLL0=1		100	
			PLL1=1, PLL0=0		50	
			PLL1=1, PLL0=1		33 $\frac{1}{3}$	
t_{CPWH}	CKREF DC	$T=1/f_{CKREF}$	0.2	0.5	0.8	T
t_{CPWL}	CKREF DC	$T=1/f_{CKREF}$	0.2	0.5	0.8	T
t_{CLKT}	LVC MOS Input Transition Time ⁽⁵⁾	10-90%			20	ns
$t_{SPWH/L}$	STROBE Pulse Width HIGH/LOW	$T=1/f_{CKREF}$	$T \times \frac{4}{14}$		$T \times \frac{10}{14}$	ns
t_{STC}	DP _(n) Setup to STROBE (DIRI=1, f=5MHz)	Setup Time 	2.5			ns
t_{HTC}	DP _(n) Hold to STROBE (DIRI=1, f=5MHz)	Hold Time 	2.0			ns

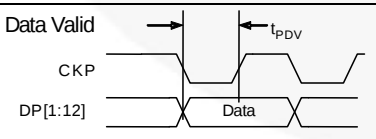
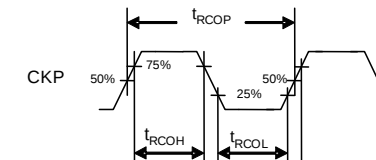
Serializer AC Electrical Characteristics

t_{TCCD}	Transmitter Clock Input to Clock Output Delay ⁽⁶⁾	 Note: STROBE=CKREF DIRI=1, $f_{CKREF}=f_{STRB}$	21a+1.5		23a+6.5	ns
------------	--	--	---------	--	---------	----

Phase Lock Loop (PLL) AC Electrical Characteristics

t_{TPLLS0}	Serializer PLL Stabilization Time	CKREF toggling and stable	200		600	µs
t_{TPLLD0}	PLL Disable Time Loss of Clock				30.0	µs
t_{TPLLD1}	PLL Power-Down Time				20.0	ns

Deserializer AC Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
t_{RCOL}		PWS1	PWS0			ns
		$f_{STRB}=f_{CKREF}$	0	0	7a+3	
		$f_{STRB}=f_{CKREF}$	0	1	7a+3	
		$f_{STRB}=.5 \times f_{CKREF}$	1	0	13a+3	
		$f_{STRB}=.5 \times f_{CKREF}$	1	1	17a+3	
t_{PDV}	 Setup: DIRI= 0, CKSI and DS are valid signals.	Data Valid to CKP HIGH (Rising Edge STROBE), $C_L=5pF$		8a-3	8a+3	ns

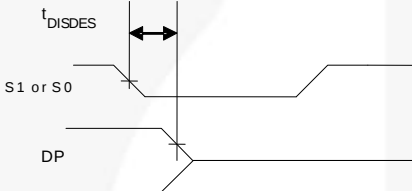
AC Electrical Characteristics (Continued)

t_{RFD}	Output Rise/Fall Time Data (20% to 80%)	$C_L=8pF$	S1=0,S0=1		3		ns
			S1=1,S0=0		8		
			S1=1,S0=1		5		
t_{RFC}	Output Rise/Fall Time CKP (20% to 80%)	$C_L=8pF$	S1=0,S0=1		2		ns
			S1=1,S0=0		7		
			S1=1,S0=1		4		

Notes:

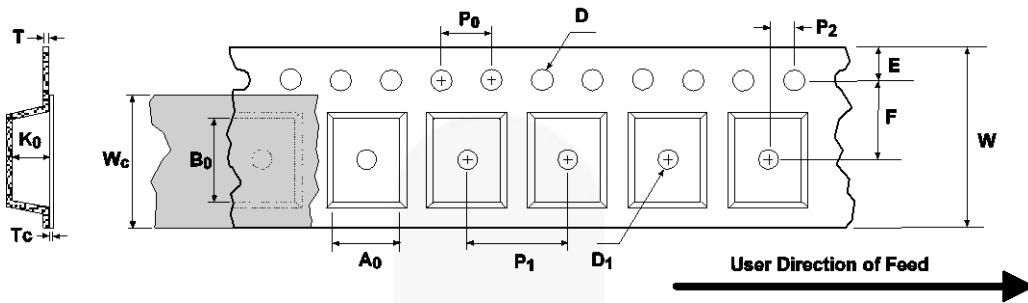
- Parameter is characterized, but not production tested.
- The average bit time “a” is a function of the serializer CKREF frequency; $a=(1/f)/14$.

Logic Timing Controls

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
t_{PHL_DIR} , t_{PLH_DIR}	Propagation Delay DIRI to /DIRO	DIRI L->H or H->L			17	ns
t_{PLZ} , t_{PHZ}	Propagation Delay DIRI to DP	DIRI L->H or H->L			25	ns
t_{DISDES}	Deserializer Disable Time: S0 or S1 LOW to DP Tri-State; DIRI=0,  Note: If S0(2) is transitioning, S1(1) must =0 for test to be valid.				25	ns
t_{DISSER}	Serializer Disable Time: S0 or S1 LOW to CKP HIGH	DIRI=1; S1(0) and S0(1)=H->L			25	ns

Tape and Reel Specifications

MLP Embossed Tape Dimensions

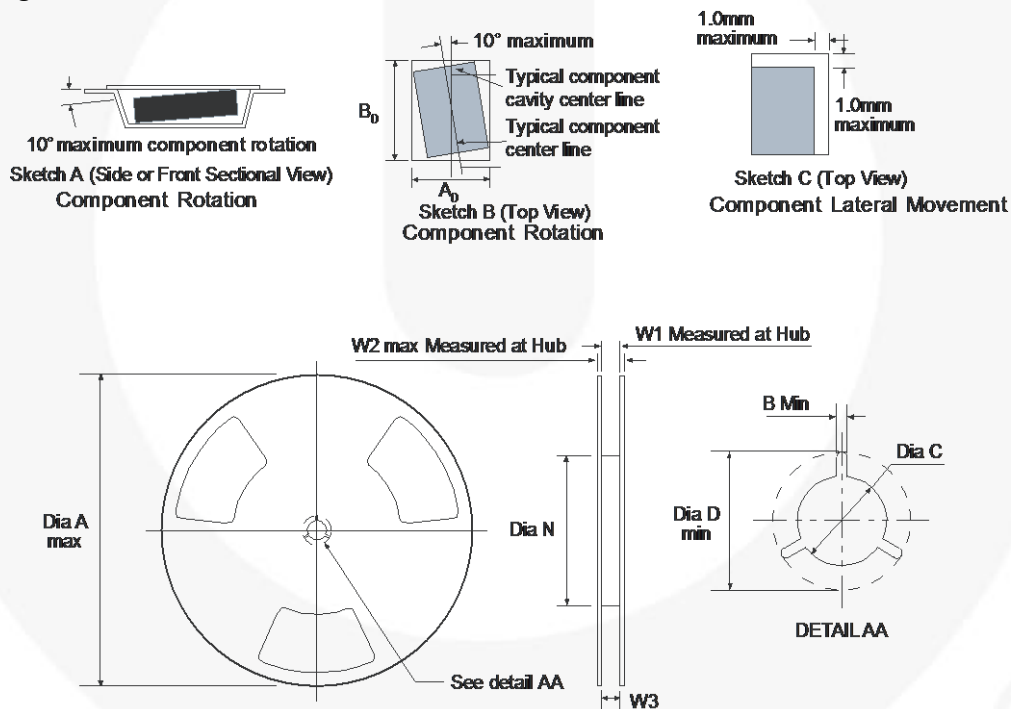


Package	A ₀ ±0.1	B ₀ ±0.1	D ±0.5	D ₁ Min.	E ±0.1	F ±0.1	K ₀ ±0.1	P ₁ Typ.	P ₀ Typ.	P ₂ ±0.5	T Typ.	T _c ±0/05	W ±0.3	W _c Typ.
5 x 5	5.35	5.35	1.55	1.50	1.75	5.50	1.40	8.00	4.00	2.00	0.30	0.07	12.00	9.30
6 x 6	5.35	5.35	1.55	1.50	1.75	5.50	1.40	8.00	4.00	2.00	0.30	0.07	12.00	9.30

Notes:

A₀, B₀, and K₀ dimensions are determined with respect to the EIA/JEDEC RS-481 rotational and lateral movement requirements (see sketches A, B, and C).

MLP Shipping Reel Dimensions

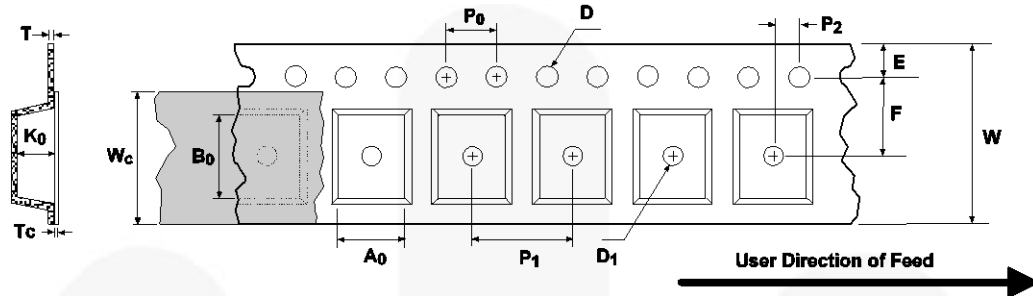


Tape Width	Dia A Max.	Dim B Min.	Dia C +0.5/-0.2	Dia D Min.	Dim N Min.	Dim W1 +2.0/-0	Dim W2	Dim W3 (LSL-USL)
8	330.0	1.5	13.0	20.2	178.0.	8.4	14.4	7.9 ~ 10.4
12	330.0	1.5	13.0	20.2	178.0.	12.4	18.4	11.9 ~ 15.4
16	330.0	1.5	13.0	20.2	178.0.	16.4	22.4	15.9 ~ 19.4

Figure 8. MLP Tape and Reel

Tape and Reel Specifications (Continued)

BGA Embossed Tape Dimensions

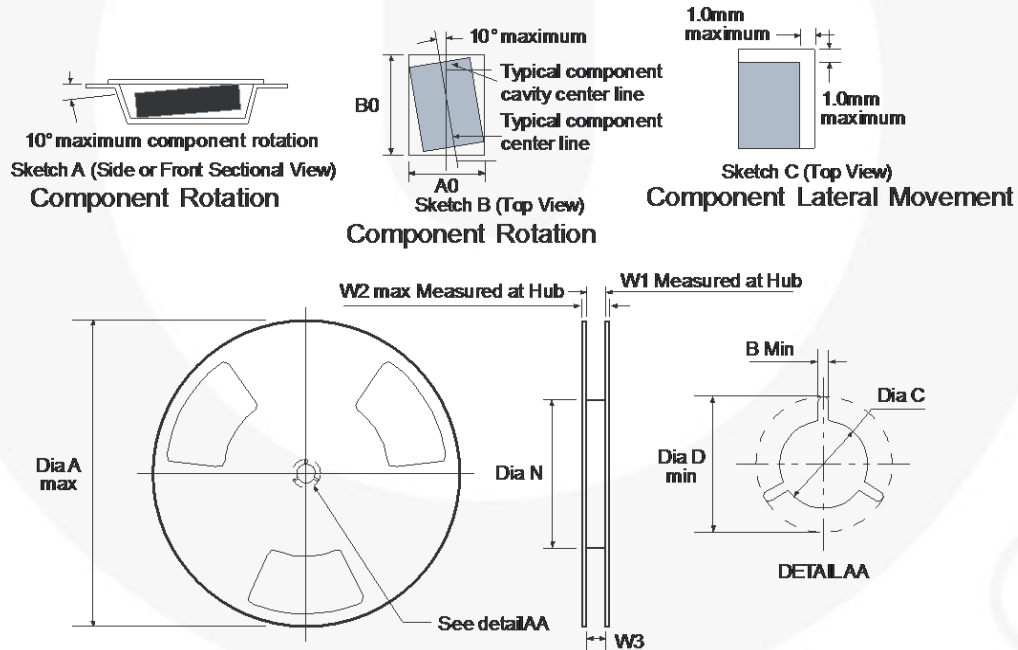


Package	A ₀ ±0.1	B ₀ ±0.1	D ±0.5	D ₁ Min.	E ±0.1	F ±0.1	K ₀ ±0.1	P ₁ Typ.	P ₀ Typ.	P ₂ ±0.5	T Typ.	T _c ±0/05	W ±0.3	W _c Typ.
3.5 x 4.5	3.85	4.80	1.55	1.50	1.75	5.50	1.10	8.00	4.00	2.00	0.30	0.07	12.00	9.3

Notes:

A₀, B₀, and K₀ dimensions are determined with respect to the EIA/JEDEC RS-481 rotational and lateral movement requirements (see sketches A, B, and C).

BGA Shipping Reel Dimensions



Tape Width	Dia A Max.	Dim B Min.	Dia C +0.5/-0.2	Dia D Min.	Dim N Min.	Dim W1 +2.0/-0	Dim W2	Dim W3 (LSL-USL)
8	330.0	1.5	13.0	20.2	178.0	8.4	14.4	7.9 ~ 10.4
12	330.0	1.5	13.0	20.2	178.0	12.4	18.4	11.9 ~ 15.4
16	330.0	1.5	13.0	20.2	178.0	16.4	22.4	15.9 ~ 19.4

Figure 9. BGA Tape and Reel

Physical Dimensions

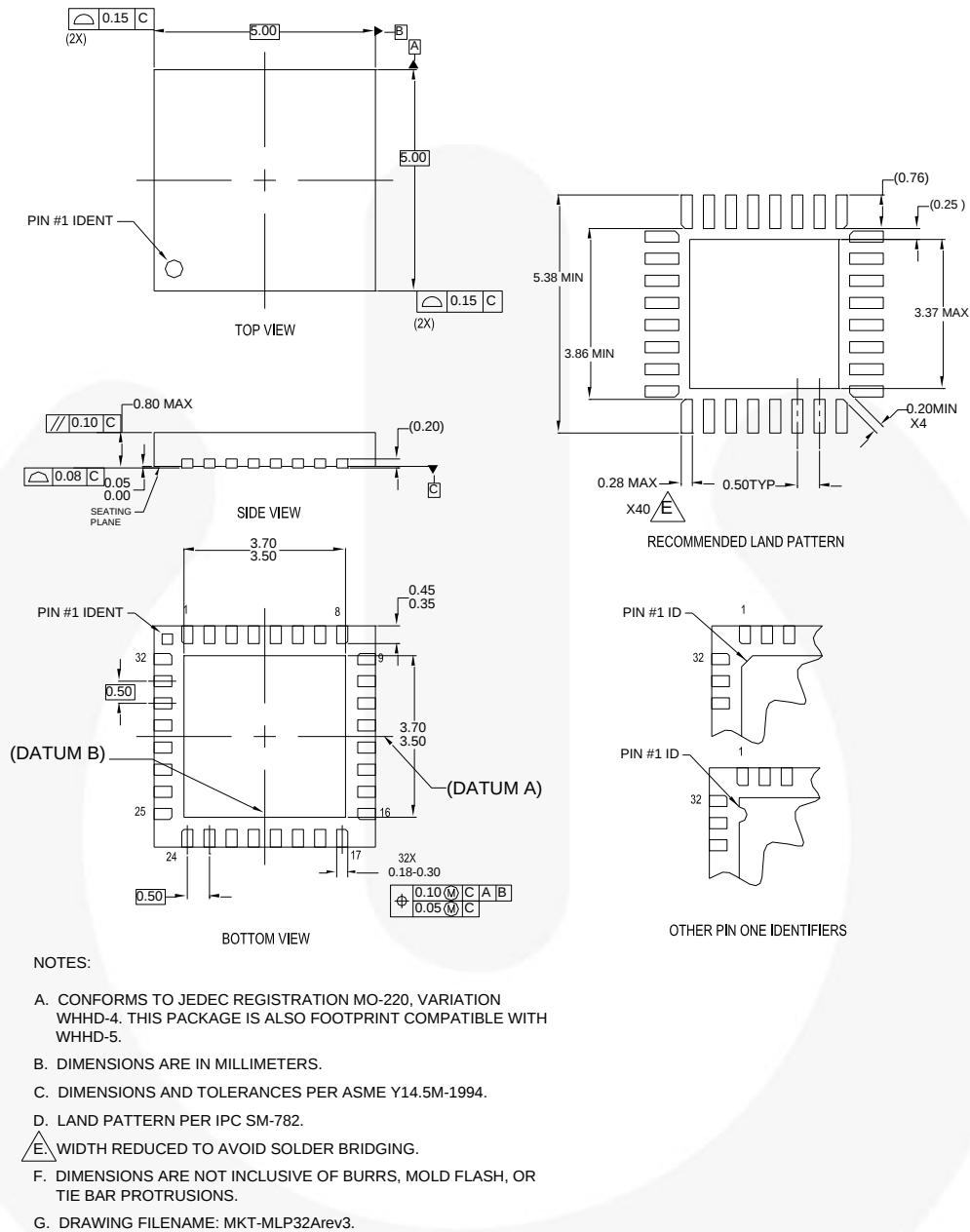


Figure 10. 32-Lead, Molded Leadless Package (MLP)

Order Number	Operating Temperature Range	Package Description	Packing Method
FIN212ACMLX	-30 to 70°C	32-Terminal Molded Leadless Package (MLP), Quad, JEDEC MO-220, 5mm Square	Tape & Reel

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: <http://www.fairchildsemi.com/packaging/>.

Physical Dimensions (Continued)

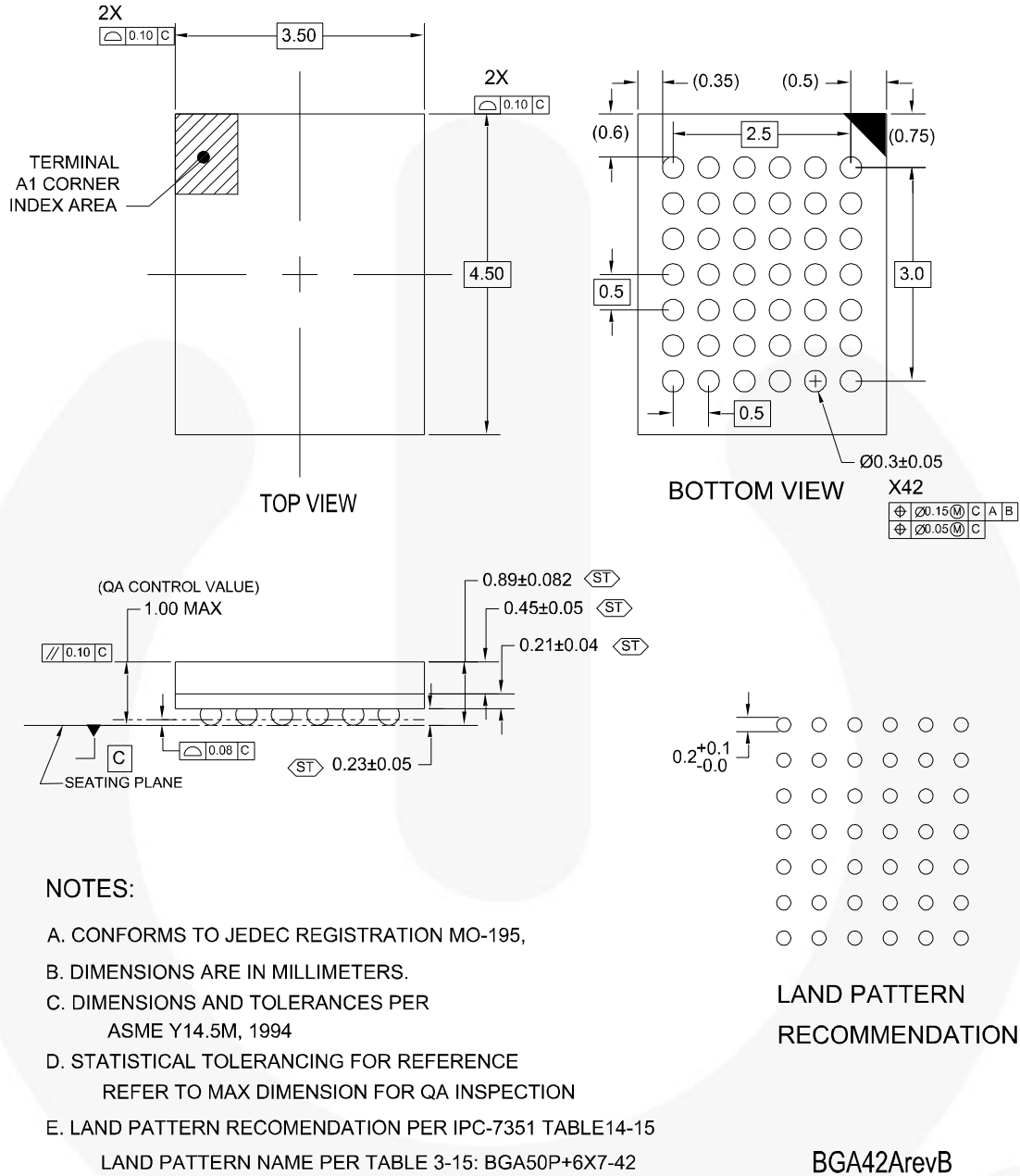


Figure 11. 42-Ball, Ball Grid Array (BGA) Package

Order Number	Operating Temperature Range	Package Description	Packing Method
FIN212ACGFX	-30 to 70°C	42-Ball Ultra Small-Scale Ball Grid Array (USS-BGA), JEDEC MO-195, 3.5 x 4.5mm Wide, 0.5mm Ball Pitch	Tape & Reel

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: <http://www.fairchildsemi.com/packaging/>.



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

2Cool™	FPS™		Sync-Lock™
AccuPower™	F-PFS™		
AX-CAP®*	FRFET®	PowerTrench®	TinyBoost™
BitSiC™	Global Power Resource™	PowerXS™	TinyBuck™
Build it Now™	GreenBridge™	Programmable Active Droop™	TinyCalc™
CorePLUS™	Green FPS™	QFET®	TinyLogic®
CorePOWER™	Green FPS™ e-Series™	QS™	TINYOPTO™
CROSSVOLT™	Gmax™	Quiet Series™	TinyPower™
CTL™	GTO™	RapidConfigure™	TinyPVM™
Current Transfer Logic™	IntelliMAX™		TinyWire™
DEUXPEED®	ISOPLANAR™	Saving our world, 1mW/W/kW at a time™	TranSiC™
Dual Cool™	Making Small Speakers Sound Louder and Better™	SignalWise™	TriFault Detect™
EcoSPARK®	MegaBuck™	SmartMax™	TRUECURRENT®*
EfficientMax™	MICROCOUPLER™	SMART START™	µSerDes™
ESBC™	MicroFET™	Solutions for Your Success™	
	MicroPak™	SPM®	UHC®
Fairchild®	MicroPak2™	STEALTH™	Ultra FRFET™
Fairchild Semiconductor®	MillerDrive™	SuperFET®	UniFET™
FACT Quiet Series™	MotionMax™	SuperSOT™-3	VCX™
FACT®	mWSaver™	SuperSOT™-6	VisualMax™
FAST®	OptoHiT™	SuperSOT™-8	VoltagePlus™
FastvCore™	OPTOLOGIC®	SupreMOS®	XS™
FETBench™	OPTOPLANAR®	SyncFET™	

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I64

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative